

ABSTRACT

A semiconductor device according to an embodiment of the present disclosure includes a first cell area and a second cell area adjacent to each other in a first direction, a support disposed between the first cell area and the second cell area, first gate lines stacked in the first cell area, first pads extended from the first gate lines and protruded upward along a first sidewall of the support, second gate lines stacked in the second cell area, second pads extended from the second gate lines and protruded upward along a second sidewall of the support, and first connection pads extended in the first direction along a third sidewall of the support and electrically connected the first pads with the second pads.

FIG. 8